



规格书编号：

SPEC NO: HDF1250A8S6SP00

产品规格书

SPECIFICATION

CUSTOMER 客 户: _____

PRODUCT 产 品: _____ SAW FILTER _____

MODEL NO 型 号: _____ HDF1250A8-S6 _____

MARKING 印 字: _____ HDF6G358 _____

PREPARED 编 制: _____ CHECKED 审 核: _____

APPROVED 批 准: _____ D A T E 日 期: _____ 2014-3-25 _____

客户确认 CUSTOMER RECEIVED:		
审核 CHECKED	批准 APPROVED	日期 DATE

无锡市好达电子有限公司
Shoulder Electronics Limited

更改历史记录
History Record

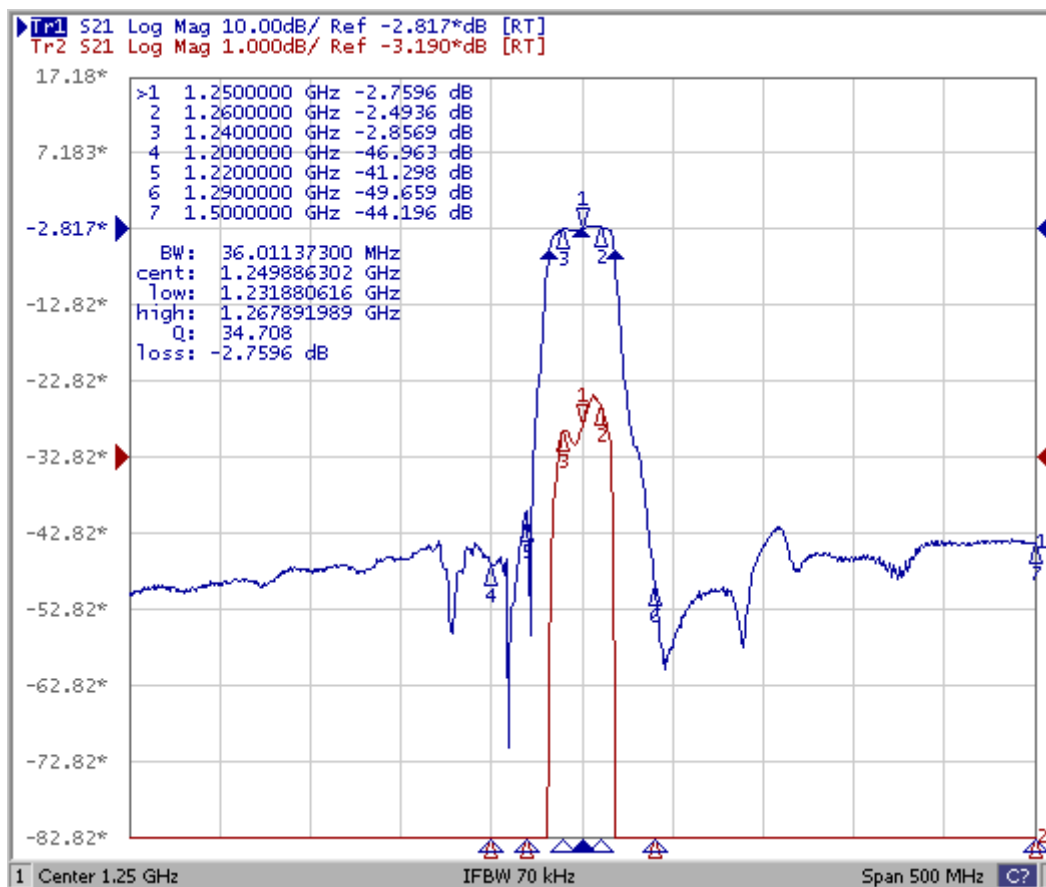
更改日期 Date	规格书编号 Spec. No.	产品型号 Part No.	客户产品型号 Customer No.	更改内容描述 Modify Content	备注 Remark

1. ELECTRICAL SPECIFICATION

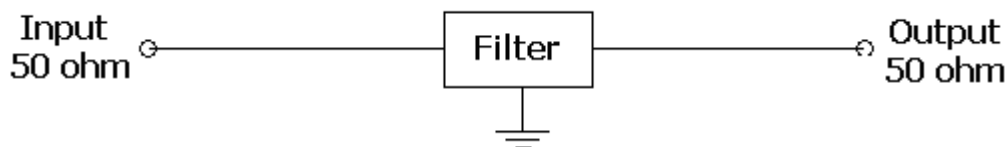
Maximum Input Power	+10dBm
DC voltage	10V
Storage Temperature Range	-45°C to +85°C
Operation Temperature Range	-40°C to +85°C

Electronic Characteristics

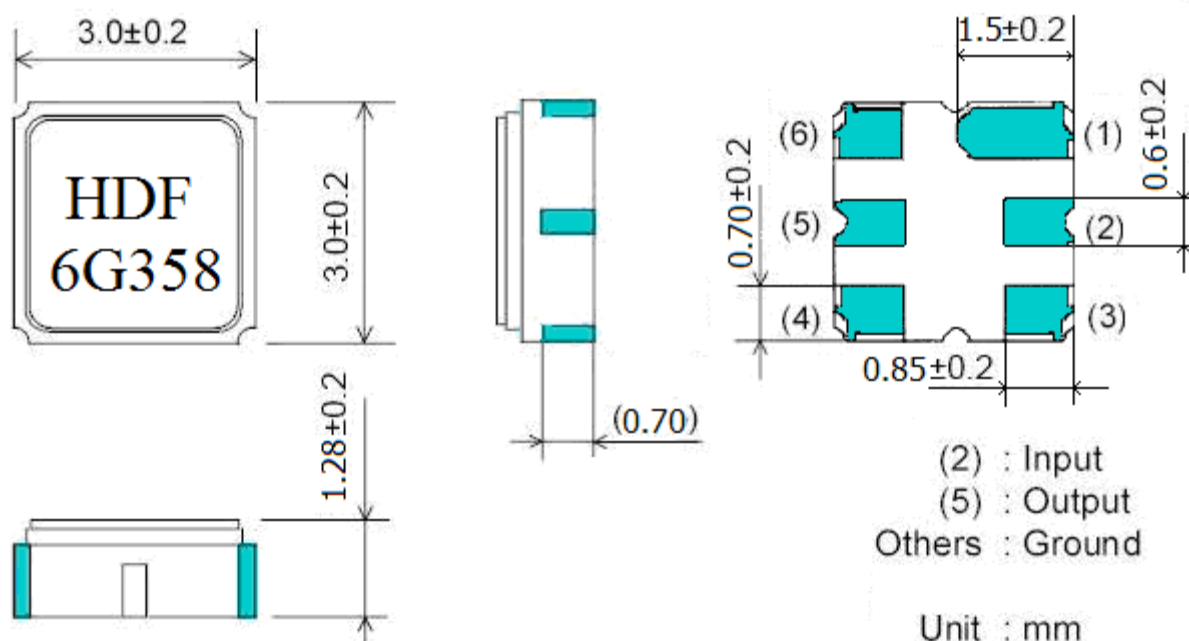
	Unit	Minimum	Typical	Maximum
Center Frequency	MHz	-	1250	-
Insertion Loss (1250 MHz)	dB		2.0	3.5
Amplitude Ripple(1250 ± 10 MHz)	dB		0.9	2.0
Absolute Attenuation				
10 ~ 1200 MHz	dB	40	50	-
1200 ~ 1220 MHz	dB	30	35	-
1290 ~ 1500 MHz	dB	40	45	-
Input/Output Impedance	Ohms		50	



2. TEST CIRCUIT



3. DIMENSION



4. ENVIRONMENTAL CHARACTERISTICS

4.1 High temperature exposure

Subject the device to +85°C for 16 hours. Then release the filter into the room conditions for 24 hours prior to the measurement. It shall fulfill the specifications in 2-2.

4.2 Low temperature exposure

Subject the device to -40°C for 16 hours. Then release the device into the room conditions for 24 hours prior to the measurement. It shall fulfill the specifications in 2-2.

4.3 Temperature cycling

Subject the device to a low temperature of -40°C for 30 minutes. Following by a high temperature of +85°C for 30 Minutes. Then release the device into the room conditions for 24 hours prior to the measurement. It shall meet the specifications in 2-2.

4.4 Resistance to solder heat

Dip the device terminals no closer than 1.5mm into the solder bath at 260°C ±10°C for 10±1 sec. Then release the device into the room conditions for 4 hours. The device shall meet the specifications in 2-2.

4.5 Solderability

Subject the device terminals into the solder bath at 245°C ±5°C for 5s, More than 95%

area of the terminals must be covered with new solder. It shall meet the specifications in 2-2.

4.6 Mechanical shock

Drop the device randomly onto the concrete floor from the height of 1m 3 times. the device shall fulfill the specifications in 2-2.

4.7 Vibration

Subject the device to the vibration for 1 hour each in x,y and z axes with the amplitude of 1.5 mm at 10 to 55 Hz. The device shall fulfill the specifications in 2-2.

5. REMARK

5.1 Static voltage

Static voltage between signal load & ground may cause deterioration & destruction of the component. Please avoid static voltage.

5.2 Ultrasonic cleaning

Ultrasonic vibration may cause deterioration & destruction of the component. Please avoid ultrasonic cleaning

5.3 Soldering

Only leads of component may be soldered. Please avoid soldering another part of component.